

Electronic Patent Application Fee Transmittal

Application Number:	10751265			
Filing Date:	02-Jan-2004			
Title of Invention:	SEMICONDUCTOR DEVICE PACKAGE DIEPAD HAVING FEATURES FORMED BY ELECTROPLATING			
First Named Inventor/Applicant Name:	Hamza Yilmaz			
Filer:	Kent J. Tobin/Robert Jackson			
Attorney Docket Number:	020964-003900US			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Certificate of correction	1811	1	100	100
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				100